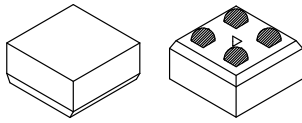


# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

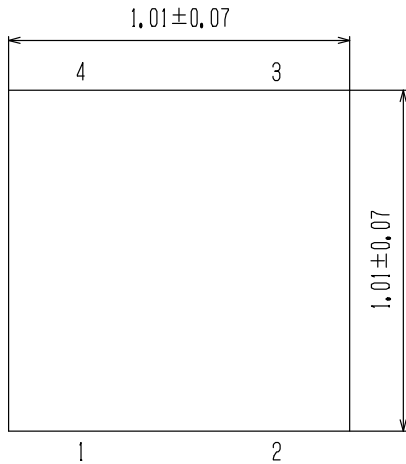
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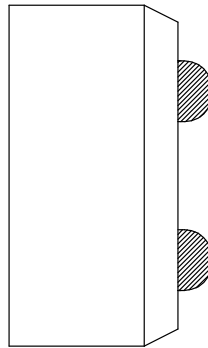
**ODCSP4 1.01x1.01**  
**CASE 570AC**  
**ISSUE O**

DATE 31 MAR 2012

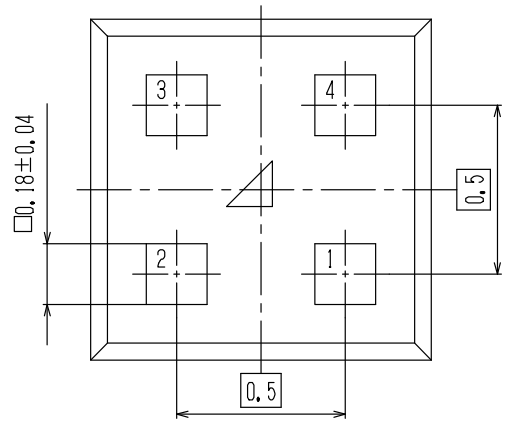
TOP VIEW



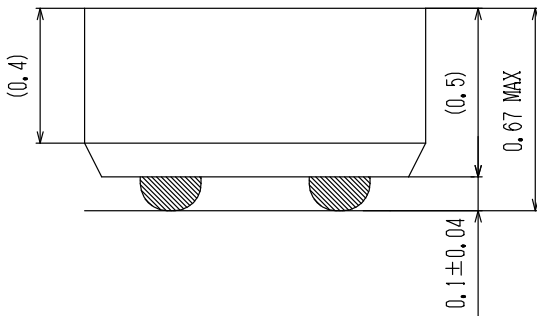
SIDE VIEW



BOTTOM VIEW



SIDE VIEW



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